**EJ/ET/EN/EX/EQ/IE/IS/IC >: < 22636> : < Emerging Trends in Electronics >:**

**< Recent Electronic Components >: <UO2c.1:** **Describe the steps involved in the SMT (Surface Mount Technology) process**.**>**

**<Assessments>: <Formative>**

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| **Set 1: Question No. 1** | **Set 1: Question No. 2** | **Set 1: Question No. 3** |
| 1. Surface-mount technology (SMT) is a method for producing\_\_\_\_\_\_\_in which the components are mounted or placed directly onto the surface of ……. | ii ) With surface mount technology(SMT) the devices should \_\_\_\_\_\_\_\_ | 1. \_\_\_\_\_\_\_\_ runs a number of quality checks for the boards visually, such as component alignment and checking for solder bridges |
| **Recall/ Remembering** | **Understanding** | **Understanding** |
| 1. Electric circuit, electric board | a) mount directly | a) reflow oven |
| 1. Electronic circuit, printed circuit board 2. Optical Light emitting display | b) have parallel connecting pins | b) SMD machine   1. Optical Light emitting display |
| 1. Pneumatic circuit, pneumatic bench | c) requires holes and pads | c) Automatic Optic Inspection machine |
| 1. d) Instrumentation circuit, control pane | d) requires PTH | d) solder paste printer |
| **Ans: (b)** | **Ans: (a)** | **Ans: (c)** |